

Preliminary Technical Information

GenX3<sup>™</sup> 600V IGBTs

## (Electrically Isolated Back Surface)

Medium-Speed Low-Vsat PT IGBTs 5-40 kHz Switching

**Test Conditions** 

Continuous

Transient

 $T_c = 25^{\circ}C$  to  $150^{\circ}C$ 

 $T_{J} = 25^{\circ}C$  to 150°C,  $R_{GE} = 1M\Omega$ 

Symbol

V<sub>CES</sub>

V<sub>CGR</sub> V<sub>ges</sub>

V<sub>GEM</sub>

I<sub>CES</sub>

GES

 $V_{CE(sat)}$ 

# **IXGR48N60B3\* IXGR48N60B3D1**

\*ObsoletePartNumber



**Maximum Ratings** 

V

V

V

V

IXGR\_B3

600 600

± 20

± 30

ISOPLUS247™

**t**<sub>fi(typ)</sub>

 $\mathbf{V}_{\text{CES}}$ 

C25

=

 $V_{CE(sat)} \leq 2.1V$ 



600V

60A

= 116ns

G = Gate E = Emitter C = Collector

### Features

- Silocon Chip on Direct-Copper Bond (DCB) Substrate
- Isolated Mounting Surface
- Optimized for Low Conduction and Switching Losses
- 2500V~ Electrical Isolation
- Anti-Parallel Ultra Fast Diode
- Square RBSOA

#### Advantages

- High Power Density
- Low Gate Drive Requirement

#### Applications

- Power Inverters
- UPS

25 µA

1.75 mA

±100 nA

V

V

2.1

1.77

1.74

- Motor Drives
- SMPS
- PFC Circuits
- Battery Chargers
- Welding Machines
- Lamp Ballasts

I <sub>C25</sub>	$T_c = 25^{\circ}C$		60		А	
I <sub>C110</sub>	$T_c = 110^{\circ}C$		27		А	
<b>I</b> <sub>F110</sub>	T <sub>c</sub> = 110°C (48N60B3D1)			A		
I <sub>CM</sub>	$T_c = 25^{\circ}C$ , 1ms		280		A	
SSOA	$V_{_{GE}} = 15V, T_{_{VJ}} = 125^{\circ}C, R_{_{G}} = 5\Omega$	I <sub>CM</sub> =	120		A	
(RBSOA)	Clamped Inductive Load	@ <	$V_{ce}$			
P <sub>c</sub>	$T_c = 25^{\circ}C$		150		W	
T		-55 +	150		°C	
T <sub>JM</sub>			150		°C	
T <sub>stg</sub>		-55 +	150		°C	
T	1.6mm (0.062 in.) from Case for 10s		300	°C		
T <sub>SOLD</sub>	Plastic Body for 10 seconds		260			
F <sub>c</sub>	Mounting Force	20120 / 4.5.	.27	N/	N/lb.	
VISOL	50/60 Hz, RM, t = 1min	25	500		V~	
Weight		5				
Symbol	Test Conditions	Characteristic Values				
$(T_{J} = 25^{\circ}C,$	Unless Otherwise Specified)	Min.	Тур.	Max.		
BV <sub>CES</sub>	$I_{c} = 250 \mu A, V_{GE} = 0 V$	600			V	
$V_{GE(th)}$	$I_{c}$ = 250 $\mu$ A, $V_{ce}$ = $V_{ge}$	3.0		5.5	V	

48N60B3

48N60B3D1

T<sub>1</sub>= 125°C

 $V_{CE} = V_{CES}, V_{GE} = 0V$ 

 $V_{ce} = 0V, V_{ge} = \pm 20V$ 

 $I_{c} = 40A, V_{GE} = 15V, Note 1$ 

Symbol Test Conditions Cha				aracteristic Values				
(T <sub>J</sub> = 25°C, l	Jnless Otherwise Specified	Min.	Тур.	Max.				
<b>g</b> <sub>fs</sub>	$I_{c} = 30A, V_{ce} = 10V, Note 1$	20	30		S			
C <sub>ies</sub>			2980		рF			
C <sub>oes</sub>	$V_{CE} = 25V, V_{GE} = 0V, f = 1MHz$	48N60B3	170		рF			
J		48N60B3D1	200		рF			
C <sub>res</sub>			45		pF			
Q_ )			115		nC			
Q <sub>ge</sub>	• $I_c = 40A, V_{GE} = 15V, V_{CE} = 0.5 \bullet$	V <sub>CES</sub>	21		nC			
Q <sub>gc</sub> )			40		nC			
t <sub>d(on)</sub>			22		ns			
ri	Inductive Load, $T_J = 25^{\circ}C$		25		ns			
E <sub>on</sub>	I <sub>c</sub> = 30A, V <sub>ge</sub> = 15V		0.84		mJ			
t d(off)	$V_{\rm CE} = 480 \text{V}, \text{ R}_{\rm G} = 5 \Omega$		130	200	ns			
t <sub>fi</sub>	Note 2		116	200	ns			
E <sub>off</sub> J			0.66	1.20	mJ			
d(on)			19		ns			
ri	Inductive Load, T <sub>J</sub> = 125°C		25		ns			
E <sub>on</sub>	$I_{c} = 30A, V_{GE} = 15V$		1.71		mJ			
t d(off)	$V_{ce} = 480V, R_{g} = 5\Omega$		190		ns			
t fi	Note 2		157		ns			
E <sub>off</sub> J			1.30		mJ			
R, Inc				0.83	°C/W			
Russ			0.15		°C/W			

## **IXGR48N60B3 IXGR48N60B3D1**

ISOPLUS247 (IXGR) Outline



.115 .024 .819 .123 .031 .840 b 2.92 0.61 20.80 15.75 5.4 0.80 .620 .635 e 45 .800 .170 .244 .190 780 3.81 5.59 4 6.20 .170 4.32 4.83 .520 .620 .540 .640 13.21 15.75 16.26 .065 .080 1.65 2.03

#### GATE DRAIN (COLLECTOR) SOURCE (EMITTER) 1

2 3

\_ 4 NO CONNECTION

NOTE: This drawing will meet all dimensions requirement of JEDEC outline TO-247AD except screw hole.

#### Reverse Diode (FRED) (D1 Version ONLY)

<b>Symbol</b> $(T_J = 25^\circ)$	Test ConditionsChaC, Unless Otherwise SpecifiedMin.	Characteristic Values Min. <sub> </sub> Typ. <sub> </sub> Max.				
V <sub>F</sub>	$I_{_{ m F}}$ = 30A, $V_{_{ m GE}}$ = 0V, Note 1 $T_{_{ m J}}$ = 150°C	1.6	2.8 V V			
I <sub>RM</sub>	$I_{F} = 30A, V_{GE} = 0V, V_{R} = 100V$ - $di_{F}/dt = 100A/\mu s$	4	A			
t <sub>rr</sub>	$I_{F} = 1A$ , -di/dt = 100A/µs, $V_{R} = 30V$ $T_{J} = 100^{\circ}C$	100	ns			
R <sub>thJC</sub> R <sub>thCS</sub>		1.5	1.5 °C/W °C/W			

Notes:

- 1. Pulse test, t  $\leq$  300µs, duty cycle, d  $\leq$  2%.
- 2. Switching times & energy losses may increase for higher  $V_{ce}$ (clamp), T<sub>J</sub> or R<sub>G</sub>.

#### PRELIMINARY TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from data gathered during objective characterizations of preliminary engineering lots; but also may yet contain some information supplied during a pre-production design evaluation. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

IXYS Reserves the Right to Change Limits, Test Conditions and Dimensions.

IXYS MOSFETs and IGBTs are covered	4,835,592	4,931,844	5,049,961	5,237,481	6,162,665	6,404,065 B1	6,683,344	6,727,585	7,005,734 B2	7,157,338B2
by one or more of the following U.S. patents:	4,850,072	5,017,508	5,063,307	5,381,025	6,259,123 B1	6,534,343	6,710,405 B2	6,759,692	7,063,975 B2	
	4,881,106	5,034,796	5,187,117	5,486,715	6,306,728 B1	6,583,505	6,710,463	6,771,478 B2	7,071,537	



Disclaimer Notice - Information furnished is believed to be accurate and reliable. However, users should independently evaluate the suitability of and test each product selected for their own applications. Littelfuse products are not designed for, and may not be used in, all applications. Read complete Disclaimer Notice at www.littelfuse.com/disclaimer-electronics.